

SURFACE MOUNT

SCHOTTKY BARRIER RECTIFIER VOLTAGE RANGE 60 Volts CURRENT 1.0 Ampere

SSM0160SGP

FEATURES

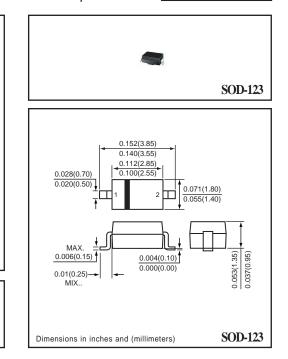
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Low profile package
- Built-in strain relief
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- High current capability, low forward voltage drop
- High surge capability
- For use in low voltage high frequency inverters, free wheeling, and polarity protection applications High temperature soldering guaranteed :
- 260°C/10 seconds at terminals

MECHANICAL DATA

Case: JEDEC SOD-123 molded plastic Terminals: Solder plated, solderable per MIL-STD-750, Method 2026 Polarity: Color band denotes cathode end Weight: 0.001 ounce 0.032 gram

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.



MAXIMUM RATINGES (At TA = 25°C unless otherwise noted)

| RATINGS | SYMBOL | SSM0160SGP | UNITS |
|--|----------|-------------|-------|
| Maximum Recurrent Peak Reverse Voltage | Vrrm | 60 | Volts |
| Maximum RMS Voltage | VRMS | 42 | Volts |
| Maximum DC Blocking Voltage | VDC | 60 | Volts |
| Maximum Average Forward Rectified Current at TL = 90°C | lo | 1.0 | Amps |
| Peak Forward Surge Current 8.3 ms single half sine-wave superimposed on rated load (JEDEC method) $TL = 70^{\circ}C$ | IFSM | 25 | Amps |
| Typical Junction Capacitance (Note 2) | CJ | 110 | pF |
| Typical Thermal Resistance (Note 1) | R θ JL | 80 | °C/W |
| Storage and Operating Temperature Range | TJ, TSTG | -65 to +125 | °C |

ELECTRICAL CHARACTERISTICS (At TA = 25°C unless otherwise noted)

| CHARACTERISTICS | | SYMBOL | SSM0160SGP | UNITS |
|---|-------------|----------------|------------|-------|
| Maximum Instantaneous Forward Voltage at 1.0 A DC | | VF | 0.55 | Volts |
| Maximum Average Reverse Current at Rated DC Blocking Voltage | @ TA = 25°C | I _R | 50 | uAmps |

NOTES: 1. Thermal Resistance (Junction to Lead) : PC Board Mounted on 0.2 X 0.2" (5 X 5mm) copper pad area. 2. Measured at 1.0 MHz and applied reverse voltage of 4.0 volts

2002-9

